

Amendments to the Specification:

Please replace the paragraph beginning at page 2, line 13, with the following redlined paragraph:

In a first solution (chip-to-chip solution), shown in Figure 2, a first chip 60 and a second chip ~~62~~ 61, which respectively integrate the power transistor 2 and the control circuit 3 (of which Figure 2 shows only one portion), are soldered on one and the same copper plate 5. In this first solution, the control circuit 3 is made using an M1-type technology, which enables integration, in a high-voltage region (*i.e.*, one able to withstand high voltages, for example 500 V), of components operating at low voltages (for example, 40 V).